SCLS077B - MARCH 1984 - REVISED MAY 1997

 Package Options Include Plastic Small-Outline (D) and Ceramic Flat (W)
Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J)
300-mil DIPs

description

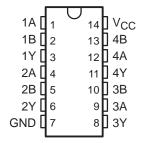
These devices contain four independent 2-input NAND gates. They perform the Boolean function $Y = \overline{A} \bullet \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic. The open-drain outputs require pullup resistors to perform correctly. They may be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

The SN54HC03 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74HC03 is characterized for operation from -40°C to 85°C.

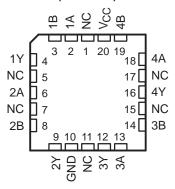
FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Н	L
L	X	Н
X	L	Н

SN54HC03 ... J OR W PACKAGE SN74HC03 ... D OR N PACKAGE (TOP VIEW)

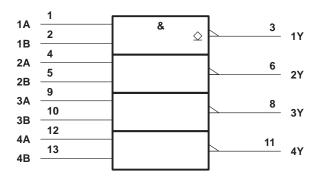


SN54HC03 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

logic diagram (positive logic)





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SN54HC03, SN74HC03 QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-DRAIN OUTPUTS

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absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V _{CC}	_0.5 V to 7	7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 r	nΑ
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 r	nΑ
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 r	nΑ
Continuous current through V _{CC} or GND	±50 r	nΑ
Package thermal impedance, θ _{JA} (see Note 2): D package		
N package	78°C	/W
Storage temperature range, T _{stq}	-65°C to 150	ľ°С

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

			SI	SN54HC03 SN74HC03			SN74HC03		LINUT
			MIN	NOM	MAX	MIN	NOM	0.5 1.35 1.8 VCC VCC 1000 500	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
ViH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		V _{CC} = 6 V	4.2			4.2			
		V _{CC} = 2 V	0		0.5	0		0.5	
٧ _{IL}	Low-level input voltage	V _{CC} = 4.5 V	0		1.35	0		1.35	V
		VCC = 6 V	0	0 1.35 0 1.35 V 0 1.8 0 1.8					
٧ı	Input voltage		0		VCC	0		VCC	V
۷o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V	0		1000	0		1000	
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V	0		500	0		500	ns
		ransition (rise and fall) time $V_{CC} = 4.5 \text{ V}$ 0 500 0 500	400						
TA	Operating free-air temperature		-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T _A = 25°C			SN54HC03		SN74HC03		UNIT	
PARAMETER	TAKAWETEK TEST CONDITIONS				TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
IOH	$V_I = V_{IH} \text{ or } V_{IL}$	AO = ACC	6 V		0.01	0.5		10		5	μΑ	
			2 V		0.002	0.1		0.1		0.1		
V _{OL} V _I = V _{IH} or V _{IL}	$I_{OL} = 20 \mu A$	I _{OL} = 20 μA	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
	$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1		0.1		0.1	V	
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33		
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33		
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA	
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			2		40		20	μΑ	
C _i			2 V to 6 V		3	10		10		10	pF	



^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

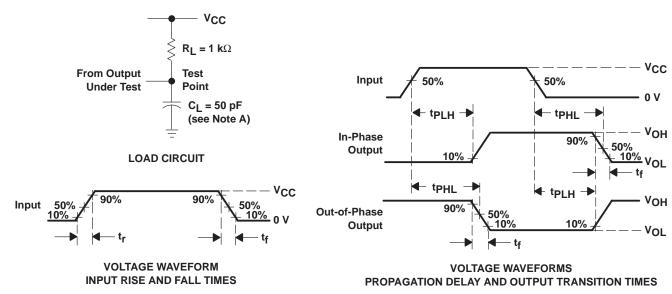
switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	V	T,	ղ = 25°C		SN54I	HC03	SN74F	1C03	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		60	105		155		131	
t _{PLH}	A or B	Υ	4.5 V		13	25		36		31	ns
			6 V		10	23		31		27	
			2 V		50	100		150		125	
t _{PHL}	A or B	Υ	4.5 V		10	20		30		25	ns
			6 V		8	17		25		21	
			2 V		38	75		110		95	
t _f		Υ	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	20	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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